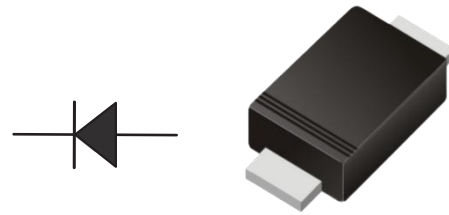


Surface Mount General Purpose Silicon Rectifiers

Parameter	Value	Unit
V_{RRM}	50~1000	V
$I_{F(AV)}$	3.0	A



SMBF

Features

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Easy to pick and place

Applications

- For use in general purpose rectification in power supplies, inverters, converters, and as freewheeling diodes for consumer and telecommunications applications.

Absolute Maximum Ratings and Characteristics (Ta=25°C unless otherwise noted)

Parameter	Symbol	S3ABF	S3BBF	S3DBF	S3GBF	S3JBF	S3KBF	S3MBF	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at $T_C=115^\circ\text{C}$	$I_{F(AV)}$	3.0							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	90							A
Maximum Instantaneous Forward Voltage at 3A	V_F	1.1							V
Maximum DC Reverse Current at Rated DC Blocking Voltage	I_R	$T_a = 25^\circ\text{C}$							μA
		$T_a = 125^\circ\text{C}$							
Typical Junction Capacitance (1)	C_j	35							pF
Typical Thermal Resistance (2)	$R_{\theta JA}$	45							$^\circ\text{C/W}$
	$R_{\theta JC}$	15							
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150							$^\circ\text{C}$

(1) Measured at 1 MHz and applied reverse voltage of 4 V.D.C

(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

Typical characteristics

Fig.1 Forward Current Derating Curve

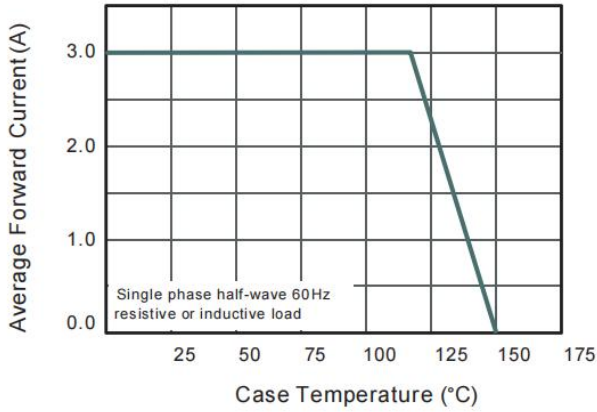


Fig.2 Typical Reverse Characteristics

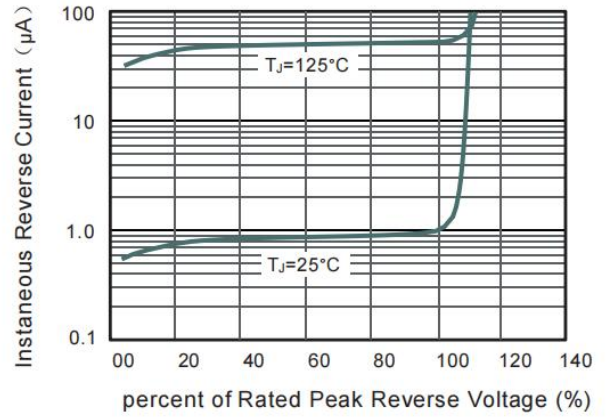


Fig.3 Typical Forward Characteristic

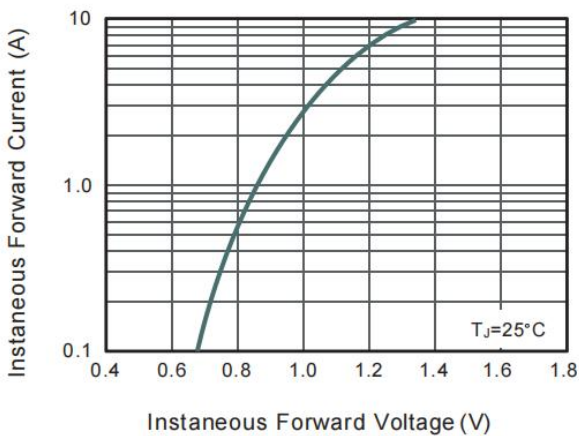


Fig.4 Typical Junction Capacitance

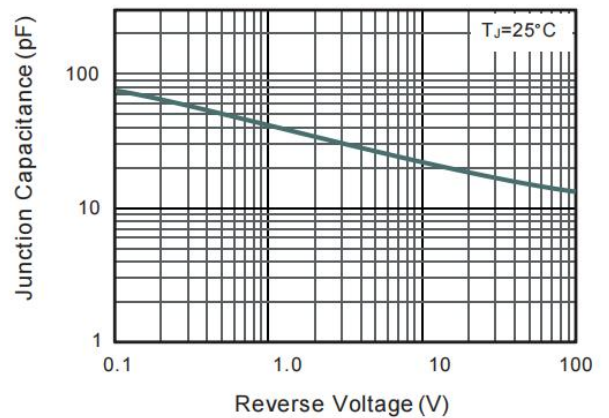
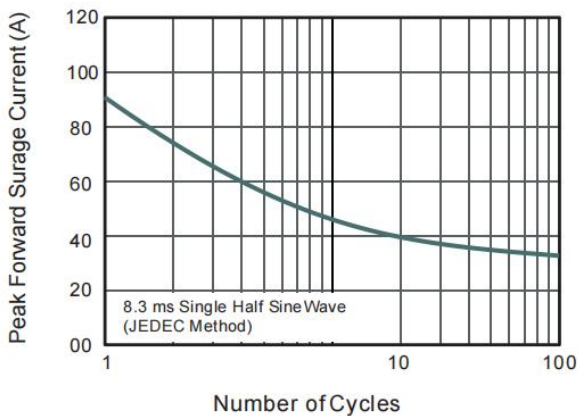
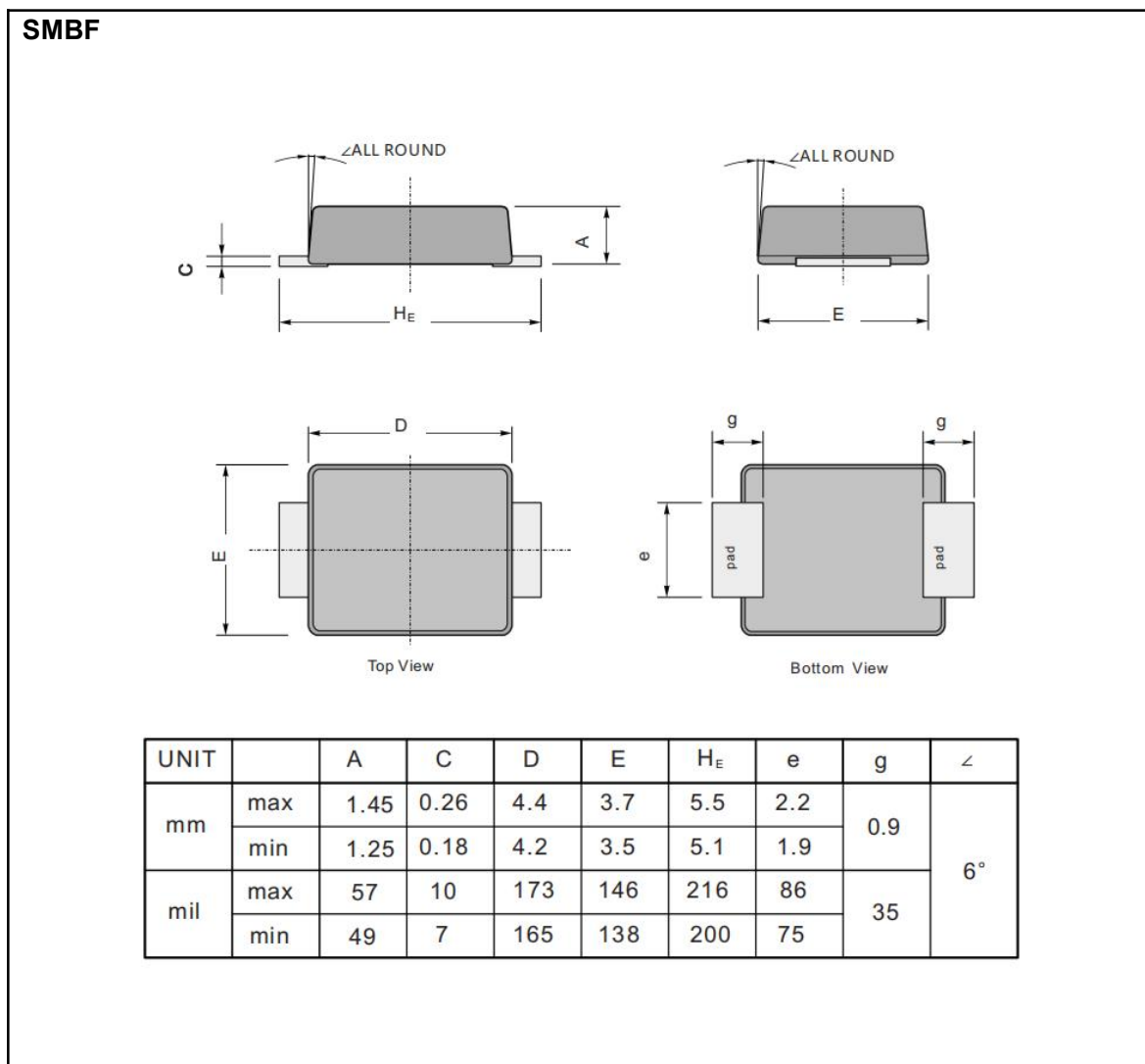


Fig.6 Maximum Non-Repetitive Peak Forward Surge Current

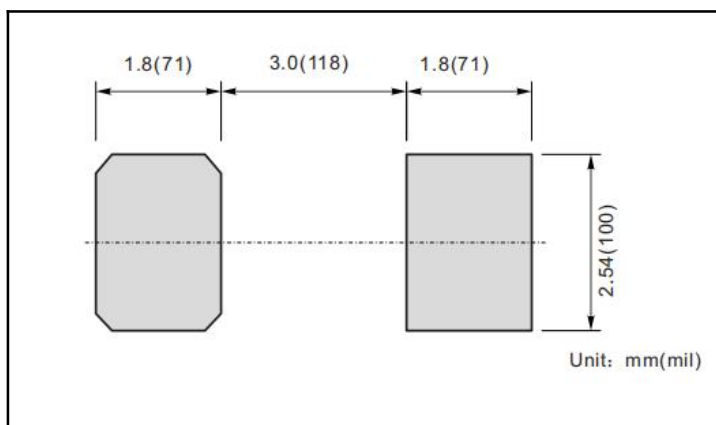


Package Outlines

Plastic surface mounted package; 2 leads



The recommended mounting pad size



Marking

Type number	Marking code
S3ABF	S3AB
S3BBF	S3BB
S3DBF	S3DB
S3GBF	S3GB
S3JBF	S3JB
S3KBF	S3KB
S3MBF	S3MB

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